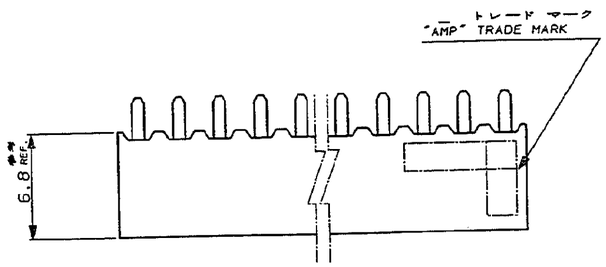
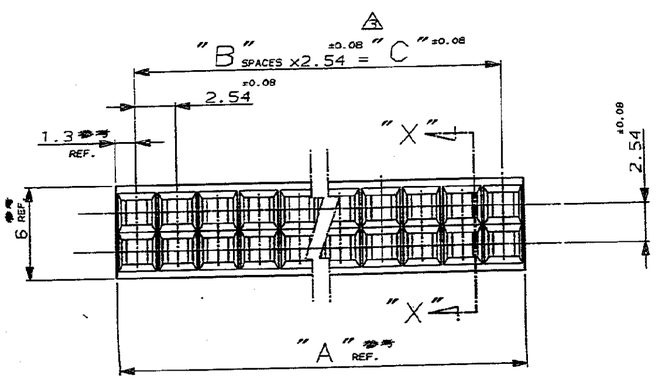
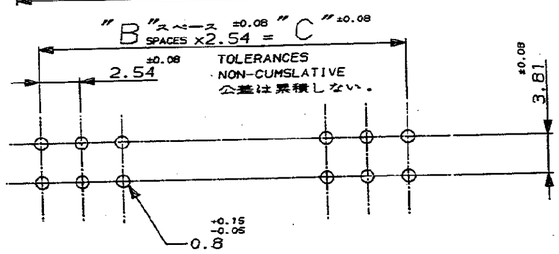
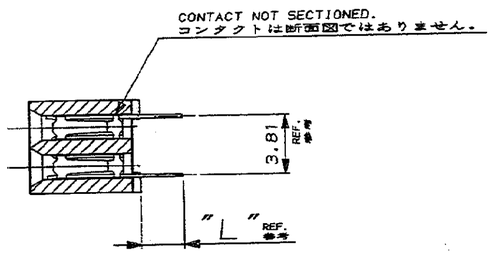






プリント基板推奨取付穴位置
RECOMMENDED HOLE LAYOUT



断面 "X"-"X"
SECT "X"-"X"

推奨基板厚 RECOMMENDED P.C.BOARD THK	"C" ±0.08	"B" スペース SPACES	"A" 参考 REF	"T" 金めっき厚 AU THK	"L" 参考 REF	極数 POS	型番 P/N
1.6±0.1					2.6		9- -0
0.3 MAX	30.48	12	33.0	0.0002MIN	1.2	26	8- -9
							~~8- -8~~
	15.24	6	17.8	0.00076MIN		14	8- -7
				0.0002MIN			8- -6
				0.0001AVE			8- -5
1.6±0.1				0.00076MIN	2.6		8- -4
				0.0002MIN			8- -3
				0.0001AVE			8- -2
0.3 MAX	10.16	4	12.7	0.00076MIN	1.2	10	8-174007-1

推奨基板厚 RECOMMENDED P.C.BOARD THK	"C" ±0.08	"B" スペース SPACES	"A" 参考 REF	"T" 金めっき厚 AU THK	"L" 参考 REF	極数 POS	型番 P/N
	48.26	19	50.8			40	8- -0
	43.18	17	45.7			36	7- -9
	40.64	16	43.2			34	7- -8
	25.40	10	27.9			22	7- -7
	22.86	9	25.4			20	7- -6
	17.78	7	20.3			16	7- -5
	7.62	3	10.2			8	7- -4
	5.08	2	7.6			6	7- -3
	2.54	1	5.1			4	7- -2
	—	—	2.5	0.0002MIN		2	7- -1
	48.26	19	50.8			40	7- -0
	43.18	17	45.7			36	6- -9
	40.64	16	43.2			34	6- -8
	25.40	10	27.9			22	6- -7
	22.86	9	25.4			20	6- -6
	17.78	7	20.3			16	6- -5
	7.62	3	10.2			8	6- -4
	5.08	2	7.6			6	6- -3
	2.54	1	5.1			4	6- -2
1.6±0.1	—	—	2.5	0.0001AVE	2.6	2	6- -1
	48.26	19	50.8			40	6- -0
	43.18	17	45.7			36	5- -9
	40.64	16	43.2			34	5- -8
	25.40	10	27.9			22	5- -7
	22.86	9	25.4			20	5- -6
	17.78	7	20.3			16	5- -5
	7.62	3	10.2			8	5- -4
	5.08	2	7.6			6	5- -3
	2.54	1	5.1			4	5- -2
	—	—	2.5	0.0002MIN		2	5- -1
	48.26	19	50.8			40	5- -0
	43.18	17	45.7			36	4- -9
	40.64	16	43.2			34	4- -8
	25.40	10	27.9			22	4- -7
	22.86	9	25.4			20	4- -6
	17.78	7	20.3			16	4- -5
	7.62	3	10.2			8	4- -4
	5.08	2	7.6			6	4- -3
	2.54	1	5.1			4	4- -2
0.3 MAX	—	—	2.5	0.0001AVE	1.2	2	4- -1
	48.26	19	50.8			40	3- -3
	22.86	9	25.4			20	3- -2
1.6±0.1	17.78	7	20.3		2.6	16	3- -1
	48.26	19	50.8			40	2- -3
	22.86	9	25.4			20	2- -2
0.3 MAX	17.78	7	20.3		1.2	16	2- -1
	30.48	12	33.0			26	2- -0
	7.62	3	10.2			8	1- -9
	2.54	1	5.1			4	1- -8
	—	—	2.5			2	1- -7
	43.18	17	45.7			36	1- -6
	40.64	16	43.2			34	1- -5
	27.94	11	30.5			24	1- -4
	25.40	10	27.9			22	1- -3
	12.70	5	15.2			12	1- -2
1.6±0.1	5.08	2	7.6		2.6	6	1- -1
	30.48	12	33.0			26	1- -0
	7.62	3	10.2			8	~~-9~~
	2.54	1	5.1			4	-8
	—	—	2.5			2	-7
	43.18	17	45.7			36	-6
	40.64	16	43.2			34	-5
	27.94	11	30.5			24	-4
	25.40	10	27.9			22	-3
	12.70	5	15.2			12	-2
0.3 MAX	5.08	2	7.6	0.00076MIN	1.2	6	174007-1

NOTES;

1. MATERIAL; HOUSING: THERMOPLASTIC UL94V-0
   RECEPTACLE CONTACT: PHOSPHOR BRONZE.
2. FINISH; CONTACT POINT: "T" THK GOLD ON NICKEL 0.0013 MIN ALL OVER.
   SOLDERING AREA: 0.001 MIN TIN-LEAD.
3. THESE DIMENSIONS APPLY TO CAVITY CENTER LINES ONLY, NOT CONTACT LOCATIONS. (TOLERANCES NON-CUMULATIVE)
4. PRODUCT SPEC: 108-5245
   APPLICATION SPEC: 114-25018

注記;

1. 材料; ハウジング: 熱可塑性ポリエステル樹脂. UL94V-0
   リセプタクル　コンタクト: 燐青銅
2. 仕上げ; 接点部: "T" 厚の金めっき. NI下地 0.0013MIN.
   半田付部: 半田めっき 0.001MIN.
3. これらの寸法は、コンタクトの中心ではなく
   ハウジング穴の中心線で測定する.
   (公差は累積しない)
4. 製品規格; 108-5245
   取付適用規格; 114-25018

LTR	REVISION RECORD	DR	CHK	DATE
G1	REVISED (ECN NO. J-1122)	I.E	Y.Y	11-8-'88
G	REVISED (ECN NO. J-12743)	I.E	S.M	26-SEP-'90
F1	ADDED NEW P/N (ECN NO. J-12396)	I.E	S.M	7-AUG-'90
F	REVISED (ECN NO. J-12016)	I.E	S.M	1-AUG-'89
E2	ADDED NEW P/N (ECN NO. J-10802)	I.E	S.M	29-MAR-'89
E1	ADDED NEW P/N (ECN NO. J-10338)	I.E	S.M	5-1-'89
E	REDRAWN (ECN NO. J-9890)	I.E	S.M	1-8-'88

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AMP
AMP (JAPAN), LTD.
Tokyo, Japan

WIRE RANGE: — mm² (AWG -)
INSULATION DIA: — mm
MATERIAL 注記△3参照 SEE NOTE △3
FINISH 注記△2参照 SEE NOTE △2
DR. I.ENOMOTO 1-8-'88
DE. I.ENOMOTO 1-8-'88
CHK. S.MANABE 1-21-'88
APP. H.TAGUCHI 1-21-'88

NAME: エコノミー アンプモジュ リセプタクル コネクター.
垂直取付型 タイン巾間 3.81タイプ
ECONOMY AMPMODU RECE CONN. 3.81 TINE WIDTH V-TYPE

GENERAL TOLERANCE: 0<≦10 : ±0.2; 10<≦30 : ±0.25; 30<≦100 : ±0.3; ANGLES : ±3°

SIZE: C | LOC: J | NUMBER: C-174007
SCALE: 4-1 | REV.: G1 | SHEET: 1 OF 1

CUSTOMER DRAWING

METRIC | 3rd ANGLE PROJECTION | NUMBER C-174007

PROJ 651-106

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J REV. 10/'83